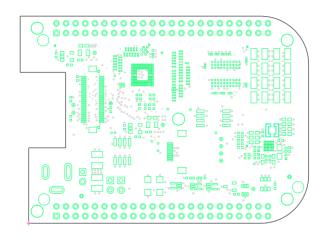
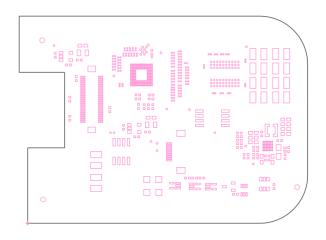
ART FILM - 111609-01_smt

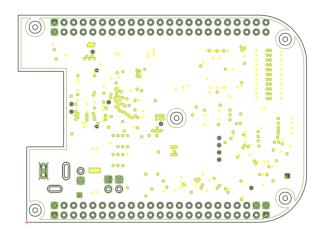


CUSTOMER NAME	TEX	AS I	NSTR	UMENT	ΓS			
BOARD NAME DLP	DLCR2000E'	VM		DESCRIP ⁻	SOLDERMASK	- PRI	MARY	SIDE
BOARD NO. 25	15210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609	- 0 1 SH	7	OF 13

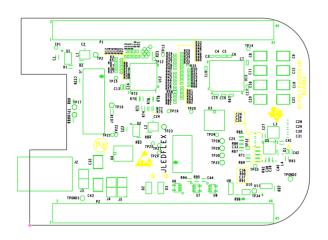
ART FILM - 111609-01_spt



CUSTOMER NAME	TEX	(AS]	S INSTRUMENTS					
BOARD NAME DLI	PDLCR2000E	VM		DESCRIP ⁻	SOLDERPASTE -	PRIMARY SIDE		
BOARD NO. 25	515210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-01	SH OF 13		

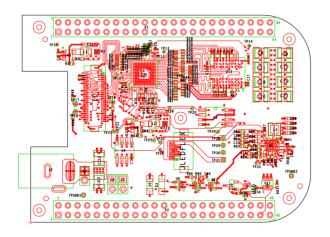


CUSTOMER NAME	TEXAS	INSTRUMENTS					
BOARD NAME DLPDLCR2000EVM DESCRIPTION LAYER 5 - GND PLANE							
BOARD NO. 251	5210 REV	DATE 1 6-SEP	-2016	PRJ# TIDLP-111609-01 SH 5 13			



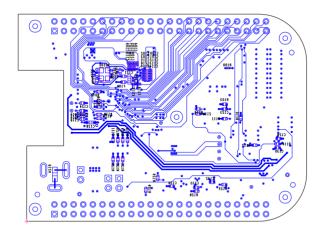
CUSTOMER NAI	ME TE)	(AS]	[NSTR	UMENT	TS		
BOARD NAME	DLPDLCR2000E	VM		DESCRIP ⁻	SILKSCREEN -	PRIMARY SI	I D E
BOARD NO.	2515210	REV E 1	DATE 6 - SEP	-2016	PRJ# TIDLP-111609-01	SH OF 1	1 3

ART FILM - 111609-01_top



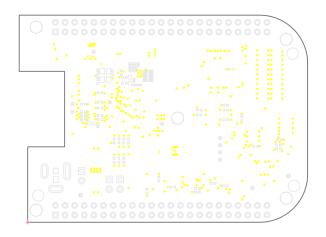
CUSTOMER NAME	TEXAS	INSTRU	UMEN1	ΓS			
BOARD NAME DLPDL	CR2000EVM		DESCRIPT		1 - PF	RIMARY	SIDE
BOARD NO. 2515	5210 REV E 1	DATE 6-SEP-	2016	PRJ# TIDLP-111	1609-01	SH 1	OF 13

ART FILM - 111609-01_bot



CUSTOMER NAME	TEXAS	INSTR	UMENT	ГЅ			
BOARD NAME DLPD	LCR2000EVM		DESCRIP ⁻		6 - SE	ECONDARY	SIDE
BOARD NO. 251	5210 REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-11:	1609-0	SH 6	OF 13

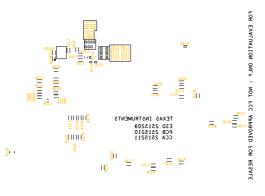
ART FILM - 111609-01_smb



CUSTOMER NAME	TEXAS	INSTRU	MENT	S		
BOARD NAME DLPD	LCR2000EVM	DE	ESCRIPT:	ION SOLDERMASK - S	SECONDARY S	IDE
BOARD NO. 251	5210 REV E 1	DATE 6-SEP-2		PRJ# TIDLP-111609-0	SH OF	13



CUSTOMER NAME	TEXAS	INSTR	UMEN	TS		
BOARD NAME DLPDL	.CR2000EVM		DESCRIP'	SILKSCREEN -	PRIMAR	Y SIDE
BOARD NO. 2515	5210 REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-01	SH 9	OF 13



CUSTOMER NAME

TEXAS INSTRUMENTS

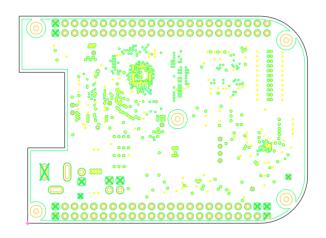
BOARD NAME
DLPDLCR2000EVM

DESCRIPTION
SILKSCREEN - SECONDARY SIDE

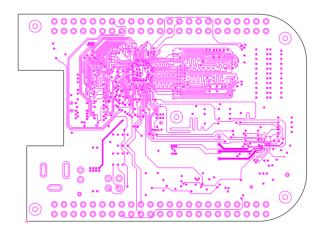
BOARD NO. 2515210

REU
E1 6-SEP-2016

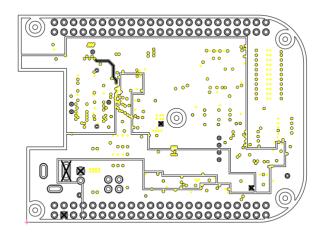
PRJ#
TIDLP-111609-01
10 13



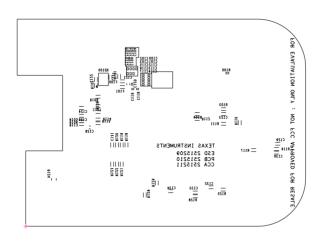
C	CUSTOMER NA	TE	XAS :	INSTR	UMENT	TS
E	BOARD NAME	DLPDLCR2000E	EVM		DESCRIP ⁻	LAYER 2 - GND PLANE
E	BOARD NO.	2515210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-01 SH 2 DF 13



CUSTOMER NAME	TEX	(AS]	NSTR	UMENT	ΓS		
BOARD NAME DLP	DLCR2000E	VM		DESCRIP ⁻	LAYER 3 - S	IGNAL	
BOARD NO. 25	15210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-0	SH 3	OF 13



CUSTOMER NAME	TEXAS	INSTR	UMENT	ΓS		
BOARD NAME DLPDI	_CR2000EVM		DESCRIP ⁻	LAYER 4	- PWR	PLANE
BOARD NO. 251	5210 REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-11160	9 - 0 1 SH	4 OF 13

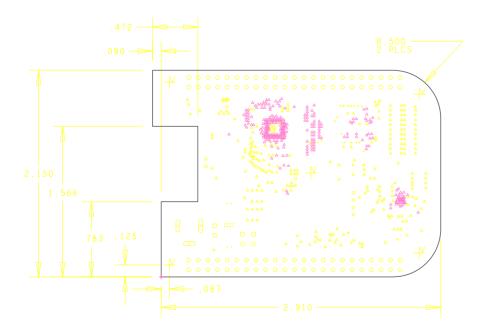


CUSTOMER NAME	TEX	(AS]	[NSTR	UMEN ⁻	TS	
BOARD NAME DLPI	DLCR2000E	VM		DESCRIP'	TION SILKSCREEN - S	ECONDARY SIDE
BOARD NO. 25	15210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-01	SH 10 OF 13

ART FILM - 111609-01_fab

DRILL CHART: TOP to BOTTOM										
	8.0									
	9.0									

	411.1	INITS ARE IN MIL	r	
SURE	SIZE	TOLERANCE	PLATED	QTY
Δ	4.0	+0.0/-4.0	PLATED	61
		NITS ARE IN MIL:		
	SIZE	TOLERANCE	PLATED	QTY
				QTY 48
GURE	SIZE 4.0 DRILL	TOLERANCE +0.0/-4.0 CHART: TOP to LY	PLATED PLATED	
	SIZE 4.0 DRILL	TOLERANCE +0.0/-4.0	PLATED PLATED	



FAB NOTES

- ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED
- 2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO
- 3. BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MFFT OR FXCFFD IPC-4101B COLOR: NATURAL
- 4. BOARD MATERIAL & CONSTRUCTION MUST MEET OR EXCEED UL94V-0.PCB MUST HAVE UL REGISTERED MATERIAL ID ON THE PCB
- 5. MINIMUM COPPER WALL THICKNESS OF PLATED-TH HOLES TO BE .001 INCH, WITH A MINIMUM
- 6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. MEASURED FROM COPPER TO COPPER.
- 7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- 9. VIAS CAN CONFORM TO CLASS 2 REQUIREMENTS AND SHOULD BE TEARDROPPED BY FAB VENDOR.
- 10. MICRO VIAS TO BE FILLED AND PLANARIZED PRIOR TO PLATING, VENDOR TO DETERMINE METHOD.

PROCESS NOTES

- 1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK
- 2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC) COLOR: GREEN. SOLDERMASK SHALL CONFORM TO TPC-SM-840 CLASS H CURRENT REV
- 3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS.
 FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
- 4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

LAYER STACK

LAYER 1 - TOP SIDE, 3/80z Cu START

100 OHMS DIFF 0.004 WIDTH/0.007 SPACE

LAYER 2 - GND PLANE, 3/8oz Cu

LAYER 3 - SIGNAL, 1/20z Cu

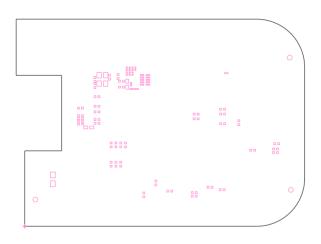
50 OHMS SE - 0.0052

LAYER 4 - PWR PLANE, 1/202 Cu

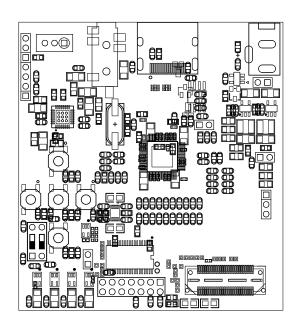
LAYER 6 - BOTTOM SIDE, 3/80z Cu START

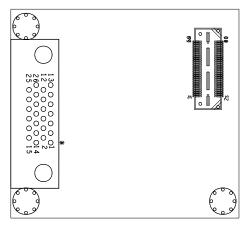
CUSTOMER NAME	TEXAS	INSTR	UMEN	TS			
BOARD NAME DLPD	LCR2000EVM		DESCRIP		RILL	DRAV	WING
BOARD NO. 251	5210 REV E1	DATE 6 - SEP	-2016	PRJ# TIDLP-11160	9-01		OF 13

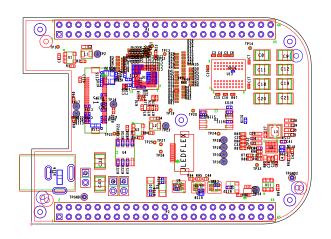
ART FILM - 111609-01_spb



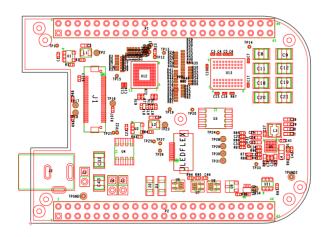
CUSTOMER NAME	TEXAS	INSTR	UMEN	TS	
BOARD NAME DLPDL	CR2000EVM		DESCRIP.	TION SOLDERPASTE - SECONDARY SI	IDE
BOARD NO. 2515	210 REV E1	DATE 6 - SEP	-2016	PRJ# TIDLP-111609-01 SH 12 1	1.3



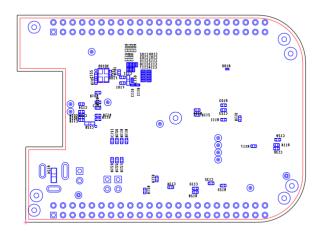




CUSTOMER NAM	TE)	(AS]	NSTR	UMENT	ΓS		
BOARD NAME	LPDLCR2000E	VM		DESCRIP	TION		
BOARD NO.	2515210	REV E 1	DATE 6-SEP-	2016	PRJ# TIDLP-111609-01	SH	OF 13

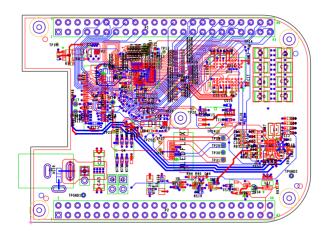


CUSTOMER NAME	TEXAS	INSTR	UMENT	TS		
BOARD NAME DLPDLCR2	000EVM		DESCRIP	TION		
BOARD NO. 2515210	REV E 1	DATE 6 - SEP	-2016	PRJ# TIDLP-111609-01	SH	OF 13

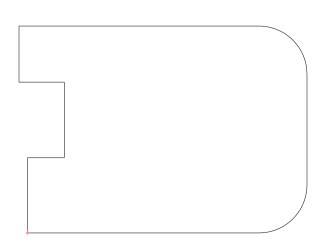


CUSTOMER NAME	TEXAS	INSTR	UMENT	TS		
BOARD NAME DLPDLCR2	000EVM		DESCRIP	TION		
BOARD NO. 2515210	REV E 1	DATE 6 - SEP	-2016	PRJ# TIDLP-111609-01	SH	OF 13

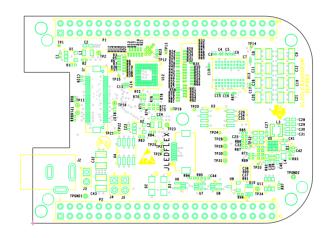
ART FILM - ROUTING



CUSTOMER NAME	TEXAS	INSTR	UMENT	ГЅ			
BOARD NAME DLPDL	CR2000EVM		DESCRIP		6 - BE	Z CMNDXR	SIDEDE
BOARD NO. 2515	5210 REV E1	DATE 6 - SEP	-2016	PRJ# TIDLP-11:	1609-01	SH 6	OF 13

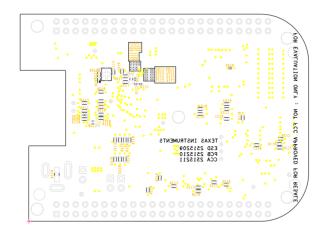


ART FILM - TSS_NO_PLOT



(CUSTOMER NAME	TE>	(AS]	[NSTR	UMENT	T S		
E	BOARD NAME DL	PDLCR2000E	VM		DESCRIP	SILKSCREEN -	PRIMARY	/ SIDE
E	30ARD NO. 2	515210	REV E 1	DATE 6-SEP	-2016	PRJ# TIDLP-111609-01	SH 9	OF 13

ART FILM - BSS_NO_PLOT



CUSTOMER NAME	TEXAS	INSTRUME	INTS
BOARD NAME DLPDLCR	2000EVM	DESCR	RIPTION SILKSCREEN - SECONDARY SIDE
BOARD NO. 251521	0 REV E 1	DATE 6-SEP-2016	PRJ# TIDLP-111609-01 SH 10 OF 13

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